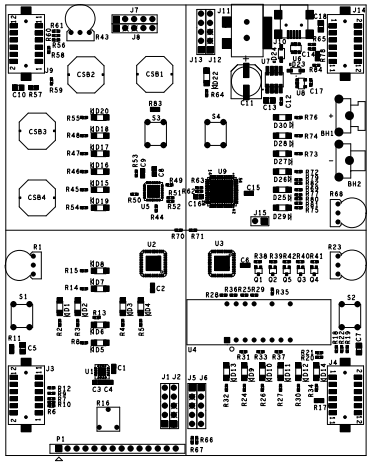
Note: X Over a pin indicates that the pin should be removed from the header.



PRIMARY SIDE

REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
*A	Additional power vias added and capsense button keepouts extended.	07/25/06	IHA
*B	Changes to silkscreen, component placement and J3, J6, J9, and J11 use new header.	11/28/06	IHA
*C	USB VBus feedback to Randon, D10 and D11 connection swap, VCC plane divided, and silk screen update to TL quadrant.,	07/11/07	IHA

NOTES:(UNLESS OTHERWISE SPECIFIED)

1. RoHS COMPLIANT CERTIFICATION OR MATERIAL DECLARATION REQUIRED
2. MATERIAL:
   A. NELCO 4000-11 OR IS420 OR EQUIVALENT. MATERIAL MUST CONFORM TO UL94V-0.
   B. USE HTE COPPER, 1/2 oz. COPPER FOIL EXTERNAL LAYERS AND 1 oz. COPPER FOIL FOR INTERNAL LAYERS.
   C. OVERALL METAL TO METAL THICKNESS .063 +/- 10%.
3. DRILLING:
   A. DIAMETERS IN DRILL TABLE ARE FINISHED HOLE SIZES +/-.003 tol. UNLESS OTHERWISE SPECIFIED IN DRILL TABLE.
   B. TEARDROP ALLOWED ON ENTRY OF VIA ON EVERY TRACE LAYER.
4. PLATING:
   COPPER PLATING IN THRU-HOLES .001 min.
5. MARKING:
   A. SILKSCREEN IN WHITE NON-CONDUCTIVE EPOXY INK ON PRIMARY SIDE OF THE BOARD OR BOTH SIDES IF APPLICABLE.
   B. FABRICATOR TO ETCH DATE CODE AND LOGO ON SECONDARY SIDE.
6. FINAL FABRICATION:
   A. SOLDRMASK PRIMARY AND SECONDARY SIDE OF BOARD USING LIQUID PHOTOIMAGABLE MASK MATERIAL OVER BARE COPPER. PER IPC-SM-840. MASK ARTWORKS PROVIDED ARE 1:1. SOLDERMASK COLOR **BLUE**
7. FINISH:
   A. SHALL BE ELECTROLYTIC NICKEL/GOLD. ELECTROLESS NIKEL / IMMERSION GOLD. (ENIG)
   B. NICKEL THICKNESS: 100-200 MICROINCHES.
   C. GOLD THICKNESS: 3-10 MICROINCHES.
8. BOARDS SHALL BE PURCHASED FROM UL RECOGNIZED VENDORS ONLY AND SHALL BE MARKED IN COPPER ON SECONDARY SIDE OF BOARD WITH VENDORS UL IDENT. FLAMABILITY RATING (94-V0), DATE CODE (WWYY), AND RoHS COMPILANT SYMBOL.
9. MANUFACTURE BOARD TO BE IN ACCORDANCE WITH PERFORMANCE STANDARD IPC-6011/6012 CLASS 2 BOARD TO BE INSPECTED PER IPC-600-A CLASS 2.
10. MAXIMUM WRAP OR TWIST SHALL NOT EXCEED .010 in/in.

UNLESS OTHERWISE SPECIFIED	SIGNATURES		DATE
DIMENSIONS ARE IN INCHES	DRAWN	IHA	07/25/06
TOLERANCES ON: ANGLES +/- 2°	CHECKED	XXX	XX/XX/XX
2 PL DECIMALS +/- .010	ENGRG	XXX	XX/XX/XX
3 PL DECIMALS +/- .005	ISSUED		
THIRD ANGLE PROJECTIONS			

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ASSEMBLY DRAWING
CY3209-ExpressEVK

SIZE	FSCM NO	DWG NO	REV
C		PDC-9349	*C

SCALE: 1/1 SHEET: 1 OF 2